BONDING THE STARS





Specifications

Mechanics

X, Y table Working area 100 x 115 mm

Resolution 0,25 μm, repeatability < 2 μm

Z-axis 60 mm

Speed up to ≤20 wires / min.

Bond head Wedge-Wedge Al - Heavy wire

Axis of rotation ± 360°

90° quick-change wire guide and cutter Bondforce programmable 100 to 1800cN

Ultrasonic system 57KHz

Wire size Aluminium wire 100... 500 µm and

Copper wire 100...300µm

Loop Forms Triangular, rectangular, reverse, stitch bond

programmable

5650

Semi-automatic Heavy Wire-WedgeBonder

The semi-automatic Wedge-Wedge Bonder 5650 fills the gap between the to the automatic bonder.

On basis of the 5600-series the bonder is fully PC controlled and allows any number of bonds to be programmed.

Pre-programmed adjust points are targeted through the camera's cross hair targeting system and the programmed bonds are executed automatically.

Two operating modes are available: Single bond for repair of various samples in order to perform a single bond.(manual-automatic) Multi wire for teaching and bonding of single chips or various samples (semi and fully automatic).

The 5650 can also be used as a Au Wire or AL Thin Wire Bonder as well as pull-/shear tester by simply replacing the bond head and loading the appropriate software.

change over time: approx. 3 minutes. Ask us for more information!

Controls

Computer Dual Core PC, 1,6 GHz processor,

4 GB RAM, Ethernet, USB 4x + 4x frontside

MonitorTFT flat screenOperation systemWindows 7

Printer All Windows-compatible printers can be installed

All bonding parameters can be printed

Work holder 2x2" standard with mechancal clamping

4x4" optional, as well with vacuum

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Other features

Programming:

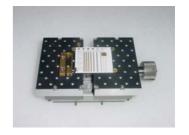
Automatic bonding of hybrids, power modules or others with programmable X/Y table

Work holders



For components up to 4 x 4"

Vacuum and mechanical clamping



For components up to 4 x 4"

Vacuum and mechanical clamping



Vacuum and mechanical clamping clamping



Vacuum and mechanical

Customised work holders are available on request.

Head Parking System For storing of temporary not required bondheads

(5610/563/5632/5650)or pull- and shear-heads Can be mounted on the left or right side of the ma-

chine

General

Camera With cross hair targeting for positioning of bonds

Microscope Stereoskop Standard 40x, other

Microscopes optional

Lighting 20 W halogen spot light, optional LED direct light

Incident light optional, ringlight, spotlight

programmable

Dimensions Height 70 cm, width 70 cm, depth 65 cm; approx. 70

kg

Supplies 100...240 VAC, single-phase, 50/60 Hz, max.500VA

Connections Air 6 bar, vacuum - 0,7 bar ø 6 mm

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